



Material Content Data Sheet



Sales Product Name		TLE7251VLE		Issued		1. August 2018		
MA#		MA001224316						
Package		PG-TSON-8-1		Weight*		27.04 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.493	5.52	5.52	55194	55194
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		109	
	non noble metal	zinc	7440-66-6	0.012	0.04		436	
	non noble metal	iron	7439-89-6	0.236	0.87		8730	
wire	non noble metal	copper	7440-50-8	9.586	35.45	36.37	354472	363747
	non noble metal	copper	7440-50-8	0.035	0.13	0.13	1306	1306
	encapsulation	organic material	carbon black	1333-86-4	0.029	0.11		1082
plastics		epoxy resin	-	1.507	5.57		55714	
	inorganic material	silicondioxide	60676-86-0	13.092	48.42	54.10	484118	540914
leadfinish	non noble metal	tin	7440-31-5	0.382	1.41	1.41	14133	14133
plating	noble metal	silver	7440-22-4	0.043	0.16	0.16	1607	1607
glue	plastics	epoxy resin	-	0.156	0.58		5775	
	noble metal	silver	7440-22-4	0.468	1.73	2.31	17324	23099
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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